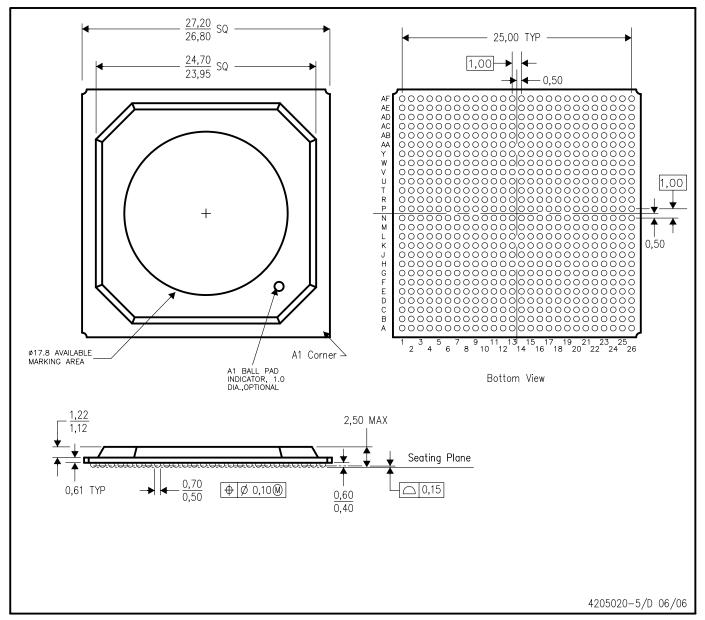
ZED (S-PBGA-N676)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. This drawing conforms to the JEDEC registered outline MS-034/A variation AAL-1.
- D. This is a lead-free solder ball design.



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